CHIPQUIK®

SMDSN60BI40

Datasheet revision 1.0 www.chipquik.com

Tin/Bismuth Solder Wire (Sn60/Bi40) 0.031" diameter - 10 ft with 2cc of SMD291 flux

Product Highlights

Low Temperature Melts at 138-170°C (281-338°F) Low Temp Tin/Bismuth Solder Wire .031" (10ft).

This non-eutectic low-temperature soldering alloy has a large melting range.

Lead-Free

RoHS 3 compliant REACH compliant

Specifications

Alloy: Sn60/Bi40 Wire diameter: 0.031" (0.8mm)

Density: 8.2g/cc

Flux Core: No flux core, solid solder wire Melting Point: 138-170°C (281-338°F)

Packaging: 10ft spool, comes with 2cc of SMD291 flux

Shelf Life: >60 months

Recommended Accessory Flux

Recommended to use with Chip Quik® SMD291 flux.

Storage and Handling

Store in a non-corrosive, dry environment.

